

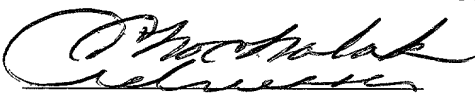
12/06/01 JC952 U.S. PTO

12-10-01

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PATENT APPLICATION
Attorney's Do. No. 9903-045

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

EXPRESS MAIL	MAILING LABEL NO. <u>EL383471365US</u> DATE OF DEPOSIT: <u>DECEMBER 6, 2001</u>
I HEREBY CERTIFY THAT THIS PAPER AND ENCLOSURES AND/OR FEE ARE BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE "EXPRESS MAIL POST OFFICE TO ADDRESSEE" SERVICE UNDER 37 CFR 1.10 ON THE DATE INDICATED ABOVE AND IS ADDRESSED TO: BOX PATENT APPLICATION, U.S. PATENT AND TRADEMARK OFFICE P.O. BOX 2327 ARLINGTON, VA 22202.	
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J1046 U.S. PTO
10/008704
12/06/01

Enclosed for filing is a patent application under 37 CFR 1.53(b) of:

Inventor Sang-Ho AHN and Se-Yong OH:
For: ULTRA-THIN SEMICODUCTOR PACKAGE DEVICE AND METHOD
FOR MANUFACTURING THE SAME

Applicant requests FIG. 3A to be published with the application.

Enclosures:

- ☒ Specification (pages 1-18); claims (pages 19-26); abstract (page 27)
- ☒ THIRTEEN sheet(s) of FORMAL drawings
- ☒ Declaration or Combined Declaration and Power of Attorney
- ☒ Newly executed (original or copy)
- ☒ Assignment with cover sheet
- Assignee Name and Address: Samsung Electronics Co., Ltd.
Suwon-city, Kyungki-do, Korea
- ☒ Certified copy of priority document 2001-11182 and 2001-38717 filed on March 5, and June 30, 2001 in Korea
- ☒ Return Postcard

CLAIMS AS FILED				
For	Number Filed	Number Extra	Rate	Basic Fee \$740
Total Claims	53-20	33	x \$ 18 =	594
Independent Claims	5-3	2	x \$ 84 =	164

